

# **TechConnect Ventures Sprint Challenge Brief:**

## Novel moisture barrier technologies for packaging

#### **BACKGROUND**

In response to client needs across a range of industries, TechConnect Ventures is calling for innovations in moisture barrier technology that can be applied to rigid and/or flexible polymer packaging applications. Our clients have expressed interest in all solution types from conceptual materials to commercially viable innovations. Effective barrier materials are critical in any type of packaging in order to maintain quality and safety standard. Of particular interest are solutions with applications in packaging for the areas of consumer goods and medical/pharmaceuticals, but any innovation with strong potential throughout the packaging sector is of considerable interest.

#### **REQUIREMENTS**

Solvers submitting an Entry should make efforts to address the following key focus areas in their Submission (if applicable):

- Moisture vapor barrier performance relative to current standards
- Any additional barrier properties (e.g. oxygen, other gases, etc.)
- Packaging application (e.g. rigid vs. flexible, food vs. medical vs. consumer goods, etc)
- Number of layers single vs multiple
- Sustainability of the solution (e.g. recyclability, biodegradability, compostability, etc.)
- Transparency of the solution

## **BUSINESS OPPORTUNITY FOR SOLVERS**

All complete and eligible Entries will be included in our exclusive Innovation Opportunity Report that will be presented the innovation-seeking clients and partners. Solvers with well-matched capabilities may be contacted directly by consortium members to discuss potential partnership opportunities. Top-rated Entries may also be invited to register or participate in an upcoming TechConnect Ventures event or pitch program.

## **PARTICIPATION RULES & GUIDELINES**

- 1. You must complete the provided Submission webform on the Sprint Submission page.
- 2. You are encouraged to submit a short presentation or pitch deck. A template is available on the Submission page.
- 3. DO NOT INCLUDE ANY INFORMATION MARKED CONFIDENTIAL, PROPRIETARY, SENSITIVE OR CLASSIFIED. SUBMISSIONS MARKED AS SUCH WILL NOT BE SHARED WITH CLIENTS.

Solvers should review the Rules and Guidelines provided on the Sprint page for full details about participation, including submission criteria, eligibility information, and more.

QUESTIONS? Contact Executive Director, Nick Kacsandi at info@techconnectventures.com